

Avionics L-Band Transistor - LDMOS

- Silicon LDMOS Technology
- $P_{OUT-PK} = 280W @ 50\mu s/2\%/50V$
- 1030MHz Operating Frequency
- Internal Impedance Pre-matched Device
- Gold Metallization System: Chip - Wire Bond - Package
- Metal Based Package Sealed With Ceramic-Epoxy Lid
- Package Size: W=1.070" (27.18mm), L=0.400" (10.16mm)
- 100% High Power RF Tested in Broadband RF Test Fixture

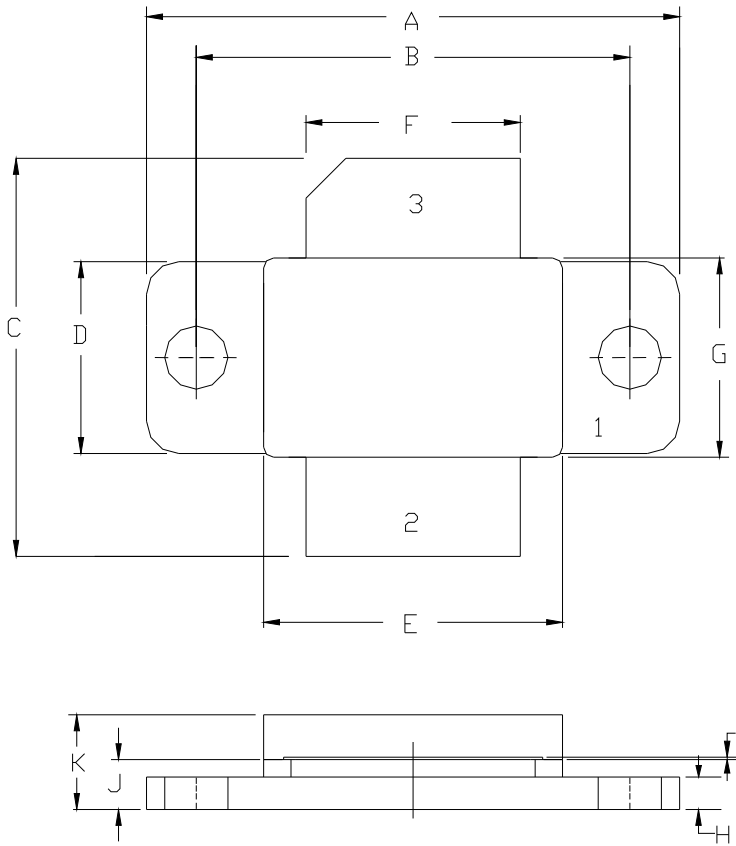


PARAMETER	SYM	MIN	TYP	MAX	UNITS	TEST CONDITIONS
DC ELECTRICAL SPECIFICATIONS						
Drain-Source Breakdown Voltage	BV_{DSS}	95	105	130	V	$I_D = 10mA, V_{GS} = 0V, T_{F1}, S1$
Drain Leakage Current	I_{DSS}	0	2	20	μA	$V_{DS} = 50V, V_{GS} = 0V, T_{F1}, S1$
Gate Threshold Voltage	V_{GS-TH}	3.0	4.0	5.0	V	$V_{DS} = 5V, I_D = 20mA, T_{F1}, S1$
RF ELECTRICAL SPECIFICATIONS						
Input Return Loss	IRL	-18	-12	-10	dB	POUT1, V1, I_{DQ1} , PW1, DF1, F1, $T_{F1}, S1$
Power Gain	Gp	17	18	19	dB	POUT1, V1, I_{DQ1} , PW1, DF1, F1, $T_{F1}, S1$
Drain Efficiency	N_D	45	55	75	%	POUT1, V1, I_{DQ1} , PW1, DF1, F1, $T_{F1}, S1$
Pulse Amplitude Droop	D	-0.40	-0.15	+0.20	dB	POUT1, V1, I_{DQ1} , PW1, DF1, F1, $T_{F1}, S1$
Load Mismatch Stability	VSWR-S	2:1	--	--	--	POUT1, V1, I_{DQ1} , PW1, DF1, F1, $T_{F1}, S1$
Load Mismatch Tolerance	LMT	20:1	--	--	--	POUT1, V1, I_{DQ1} , PW1, DF1, F1, T_{F1}, BD
DC & RF TEST CONDITIONS						
Output Power 1	POUT1	--	280	--	W	--
Drain Supply Voltage 1	V1	--		50.0	V	--
Quiescent Drain Current 1	I_{DQ1}	--		20	mA	--
Pulse Width 1	PW1	--		50	μs	--
Duty Factor 1	DF1	--		2	%	--
Frequency 1	F1	--	1030	--	MHz	--
Flange Temperature 1	T_{F1}	25	30	35	$^{\circ}C$	--
Screening Level 1	S1	100	--	--	%	--
Parameter Qualified By Design	BD	--	--	--	--	--

PARAMETER	SYM	MIN	MAX	UNITS	SCREEN	CONDITIONS
MAXIMUM RATINGS						
Drain-Source Voltage	V_{DS}	--	50	V	BD	$T_F = 25^\circ\text{C}$
Gate-Source Voltage	V_{GS}	-12	20	V	BD	$T_F = 25^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55	+150	$^\circ\text{C}$	BD	--
Operating Junction Temperature	T_J	-55	+200	$^\circ\text{C}$	BD	--
PROCESS SPECIFICATIONS						
DC Wafer Probe	--	--	--	--	100%	Per Integra Spec
Wafer DC, RF Qualification	--	--	--	--	Q1	Per Integra Spec
Wire Bond Strength	--	--	--	--	LM	Per Integra Spec
Pre-cap Visual Inspection	--	--	--	--	100%	Per Integra Spec
Gross Leak Test – MIL-STD-750D	--	--	--	--	100%	Method 1071.6 C
THERMAL RESISTANCE						
Peak Thermal Resistance Per Rated RF Specification	$R_{TH(JC)}$	--	0.033	$^\circ\text{C/W}$	BD	$T_F = 25^\circ\text{C}$
SCREENING LEVELS						
Parameter Qualified By Design	BD	--	--	--	--	--
Parameter Qualified By 3 Pieces (min) Per Wafer	Q1	--	--	--	--	--
Parameter Qualified By Assembly Line Monitor	LM	--	--	--	--	--

RF TEST FIXTURE		
▶ Broadband RF Test Fixture. Provides Device Impedance Matching to 50Ω at the Rated Operating Frequency.		
▶ Electronic CAD Drawing File Available Upon Request. Includes Circuit Dimensions and Parts List.		
▶ Reference Design PCB: Rogers , 6010.2-025-1/1, 25 mil, 1/1 oz. copper, DK=10.2.		
FREQUENCY (MHz)	$Z_{IF}(\Omega)$	$Z_{OF}(\Omega)$
1030	2.2 - j 2.4	1.1 - j 0.2
Impedance Definition		

PACKAGE OUTLINE DRAWING



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.065	1.075	27.05	27.30
B	0.865	0.875	21.97	22.22
C	0.794	0.804	20.17	20.42
D	0.380	0.390	9.65	9.90
E	0.595	0.605	15.11	15.37
F	0.425	0.435	10.79	11.05
G	0.395	0.405	10.03	10.29
H	0.060	0.070	1.52	1.78
I	0.004	0.006	0.10	0.15
J	0.096	0.106	2.44	2.69
K	0.184	0.196	4.67	4.98

PIN SCHEDULE	
1	SOURCE
2	GATE
3	DRAIN

DEFINITIONS	
DATA SHEET STATUS	
Proposed Specification	This data sheet contains proposed specifications.
Preliminary Specification	This data sheet contains specifications based on preliminary measurements and data.
Product Specification	This data sheet contains final product specifications.
MAXIMUM RATINGS	
Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.	

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